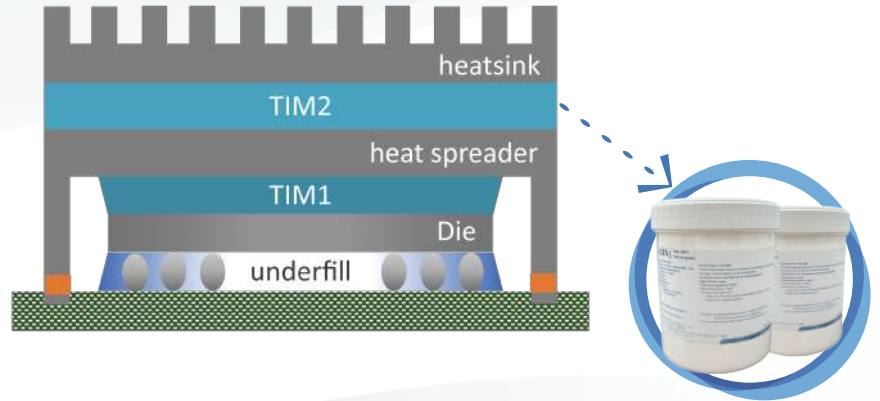


導熱膏 (TIM 2) Thermal interface material

● 特性 / Features

- 高導熱性
- 無需固化
- 無分層問題
- 易於填充接觸面
- 在高溫下極低重量損失
- 良好穩定性及緩慢乾燥速率



導熱膏是一種具有良好導熱性的熱界面材料(下稱TIM2)，其係用於填充兩種材料接觸面上的微孔隙和不平孔洞。TIM2具有無需固化之特性，係藉由在材料界面上施加特定壓力來固定及填充在電子元件(如晶圓蓋板與散熱鰭片)間的導熱膏，以建立良好導熱通道。隨著對熱管理的更高要求，GTA提出了創新和優化的TIM2，使產品能有效改善元件間的傳熱效率，對電子設備的性能、使用壽命和穩定性起著重要作用。TIM2可廣泛應用於電子產品、汽車電子、電信、消費電子、LED、液晶電視等，也可用於任何需要熱管理解決方案的應用。

● 規格 / Specification

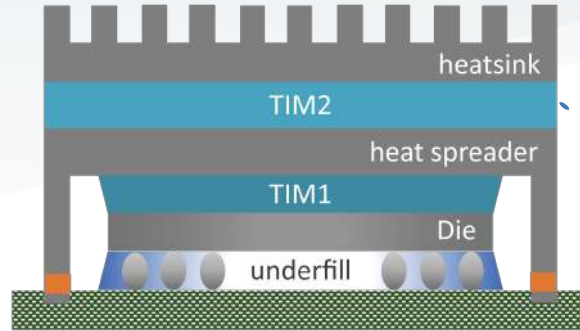
產品名稱	HSG-358	HSG-508	HSG-601	HSG-602
顏色	灰	灰	灰	灰
熱導率 (W/m · K)	3.5	5.0	6.0	6.0
熱阻值 (°C·cm ² /W) BLT(μm)	0.09 50	0.10 60	0.150 70	0.10 70
比重@25°C	2.3	2.3	2.3	2.3
黏度@25°C (Pa · s)	250	350	200	450
揮發率@150°C/24h(%)	<0.7	<0.7	2~3	<0.7
擊穿電壓 (KV/mm)	<0.5	<0.5	<0.5	<0.5
溶劑	無	無	有	無



TIM 2 Thermal interface material

Features

- No curing required
- No delamination issues
- High thermal conductivity
- Easy to fill the contact surface
- Good stability and slow drying speed
- Minimal weight loss at high temperature



Thermal grease is a thermal interface material (hereinafter referred to as TIM2) with good thermal conductivity, which is designed for filling the micro voids and uneven holes on the contact surface of the two materials. Since TIM2 has no curing required feature, the thermal grease between the lid and the heat sink within the electronic elements is fixed and filled by applying certain pressure on the interface of materials to establish a good thermal conduction channel. With the higher requirements of the thermal management, the innovation and optimization of TIM2 is put forward by GTA. This product can effectively improve the heat transfer between materials and plays an important role in the performance, service life and stability of electronic equipment. TIM2 can be widely used in electronic products, automotive electronics, telecommunications, consumer electronics, LEDs, LCD TVs, etc..., also can used in any application that requires a solution of thermal management.

Specification

Product Name	HSG-358	HSG-508	HSG-601	HSG-602
Color	Gray	Gray	Gray	Gray
Thermal conductivity (W/m·K)	3.5	5.0	6.0	6.0
Thermal resistance (°C·cm ² /W) BLT(μm)	0.09 50	0.10 60	0.150 70	0.10 70
Specific gravity@25°C	2.3	2.3	2.3	2.3
Viscosity@25°C (Pa·s)	250	350	200	450
Evaporation@150°C/24h(%)	<0.7	<0.7	2~3	<0.7
Breakdown voltage (KV/mm)	<0.5	<0.5	<0.5	<0.5
Solvent	No	No	Yes	No

